APPARATUS AND METHOD FOR PRINTING MICRO METAL STRUCTURES

Abstract

A method and device for printing liquid material such as liquid solder is provided. C4 structures as small as 10 microns in diameter can be produced using devices and methods described above. Further, devices and methods provided are able to operate at temperatures much higher than other print head designs such as piezoelectric actuated print heads. Additionally, due to the use of a gas flow restricting device and a recharging gas supply, ejection devices as described above can be used for a substantially extended lifetime, thus making devices and methods described above more economically desirable.